



## PATENT

2813

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

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3-31-03  
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**Group Art Unit: 2813**

Examiner: Thanh T. Nguyen

Serial No.: 09/981,505

Confirmation No.: 6914

Filed: October 16, 2001

**For: PLANARIZATION OF METAL  
LAYERS ON A SEMI-  
CONDUCTOR WAFER  
THROUGH NON-CONTACT DE-  
PLATING AND CONTROL WITH  
ENDPOINT DETECTION**

Commissioner for Patents  
Washington, D.C. 20231

**CERTIFICATE OF MAILING**  
**37 CFR 1.8**

I hereby certify that this correspondence is being deposited on 3/20, 2003 with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231.

3/20/03

Kent & Jones

Date \_\_\_\_\_

Signature \_\_\_\_\_

Dear Sir:

**RESPONSE TO RESTRICTION REQUIREMENT DATED FEBRUARY 25, 2003**

In response to the Restriction Requirement dated February 25, 2003, having a shortened statutory period for response set to expire on March 25, 2003, please enter this response and reconsider the claims pending in the application for reasons discussed below. Although Applicant believes that no fee is due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/AMAT/6072/KMT, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

TECHNOLOGY CENTER 2800C

MAR 21 2003

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